

Title (en)
REGENERATION METHOD FOR A PLATING SOLUTION

Title (de)
REGENERATIONSVERFAHREN FÜR EINE PLATTIERUNGSLÖSUNG

Title (fr)
PROCEDE DE REGENERATION POUR SOLUTION DE PLAQUAGE

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Application
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Abstract (en)
[origin: WO03004725A2] The invention relates to a method of depositing a layer of metal and to a method of regenerating a solution containing metal ions in a high oxidation state. To regenerate tin ions consumed from a tin plating solution by metal deposition, it has been known in the art to carry the plating solution over metallic tin to cause tin (II) ions to form. However, the amount of tin contained in thus regenerated baths slowly and continuously increases. The solution to this problem is to utilize an electrolytic regeneration cell that is provided with at least one auxiliary cathode and with at least one auxiliary anode. Tin serving for regeneration is electrolytically deposited from the solution onto the at least one auxiliary cathode in the electrolytic regeneration cell. The solution is carried over the tin serving for regeneration in order to reduce formed tin (IV) ions to tin (II) ions.

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